/ Absolute Maximum Ratings(Ta=25)

v ῼ Parameter	ɥ ᴺ Symbol	ῼӫ Rating	ᴅ ʮ Unit
Peak pulse power (t_p = 8/20μs)	P_K	69	W
Peak pulse current (t_p = 8/20μs)	I_{PP}	5.5	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	±30	KV
ESD according to IEC61000-4-2 contact discharge		±30	
Junction temperature	T_J	150	
Storage temperature	T_{STG}	-55~+150	

/ Electrical Characteristics(Ta=25)

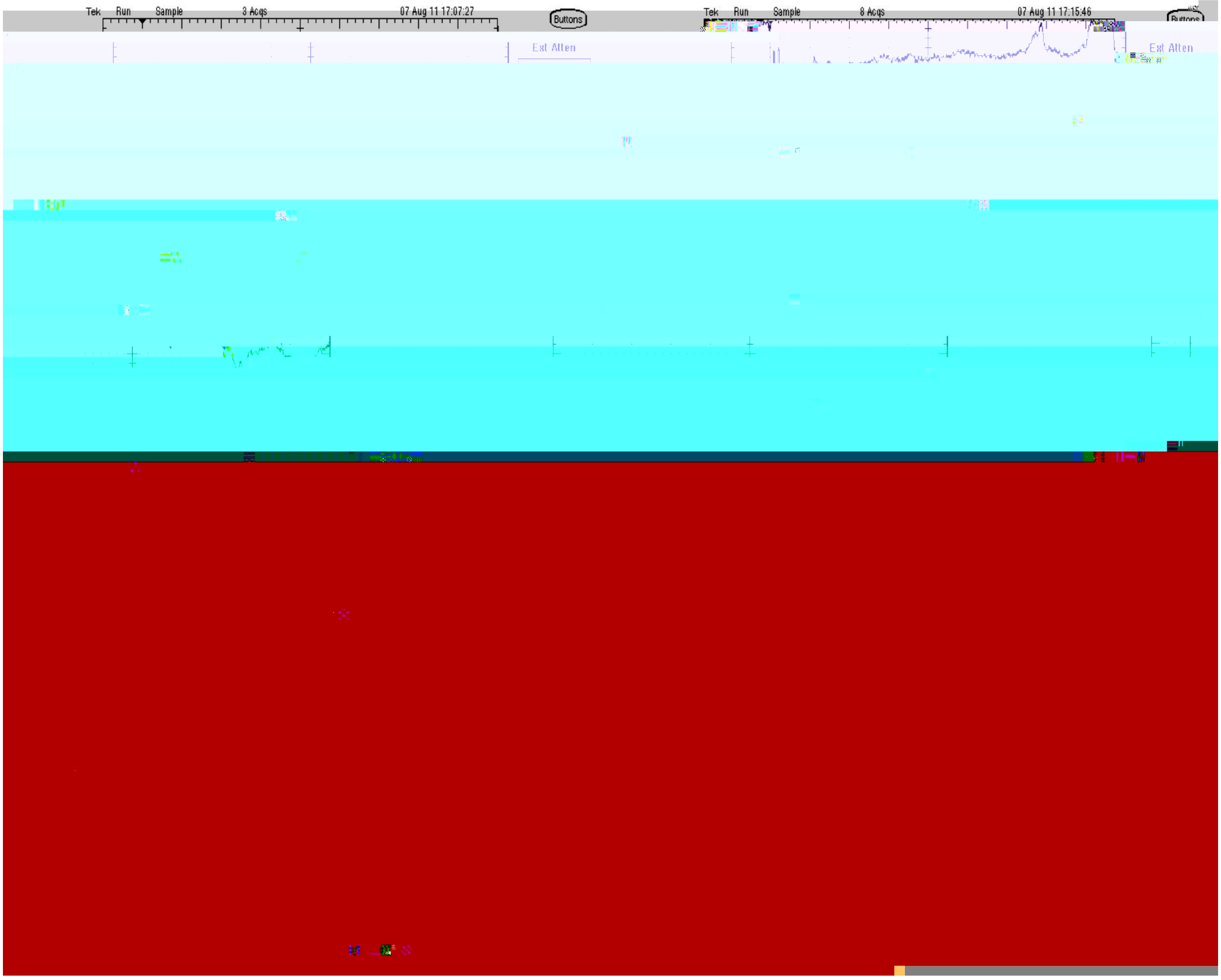
v ῼ Parameter	ɥ ᴺ Symbol	╜ ꞉ᶵ ʈ Test Conditions	ῳ ṇ ӫ Min	Ɛ ʒ ӫ Typ	ῳ ᶾ ӫ Max	ᴅ ʮ Unit
Reverse maximum working voltage	V_{RWM}				3.3	V
Reverse leakage current	I_R	V_{RWM} =3.3V			0.1	uA
Reverse breakdown voltage[1)]	V_{BR}	I_T = 1mA	5.0		6.8	V
Clamping voltage [2)]	V_C	I_{PP} = 1A t_p = 8/20μs			9.8	V
		I_{PP} = 5.5A t_p = 8/20μs			12.5	V
Junction capacitance	C_J	V_R = 0V f = 1MHz			15	pF

Notes:

1) V_{BR} is measured with a pulse test current IT at an ambient temperature of 25 ł .

2) Non-repetitive current pulse, according to IEC61000-4-5.

/ Electrical Characteristic Curve

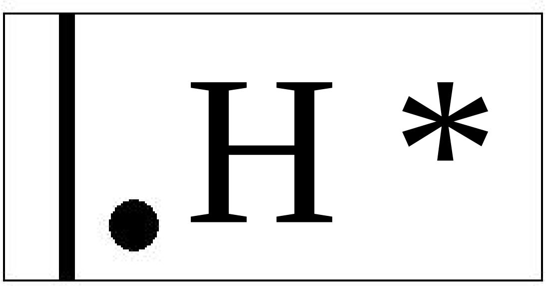


/ Package Dimensions

DFN0603

Unit:mm

/ Marking Instructions



ب ˝ χ

K χ	ʜѫ ʒ ᴺ Ꮒ
- χ	ʜѫ ˑl ғ ῆ ᴺ Ꮒ ι ҿ ˑl ғ ῆ ᴺ ψ ק

Note χ

H χ	Product Type
* χ	Lot No. Code,code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

ب ˝ χ
1 أ ♬ □ ẙ 150 Ḱ 180 ɫ ı `H ڑ 60 Ḱ 90sec;
2 Ś Ӫ □ ẙ 245 ° 5 ɫ ı `H ڑ ʽY ﾊ 㵎 5 ° 0.5sec;
3 ì˙ ˥˛ ɔ ﻪ ẙ 㵎 2 Ḱ 10 ɫ /sec.

Note:
1.Preheating:150~180 ɫ , Time:60~90sec.
2.Peak Temp.:245 ° 5 ɫ , Duration:5 ° 0.5sec.
3. Cooling Speed: 2~10 ɫ /sec.

/ Resistance to Soldering Heat Test Conditions

605 ° 5 ɫ